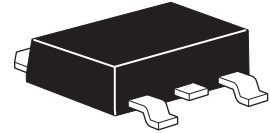


ZXMP6A16K

60V DPAK P-channel enhancement mode MOSFET

Summary

$V_{(BR)DSS}$	$R_{DS(on)}$ (Ω)	I_D (A)
-60	0.085 @ $V_{GS} = -10V$	8.2
	0.125 @ $V_{GS} = -4.5V$	6.75



Description

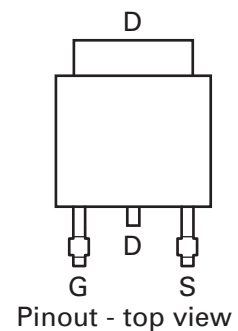
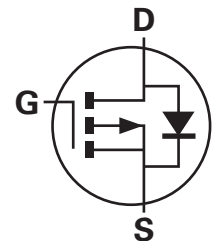
This new generation trench MOSFET from Zetex features a unique structure combining the benefits of low on-resistance and fast switching, making it ideal for high efficiency power management applications.

Features

- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- DPAK package

Applications

- DC-DC converters
- Power management functions
- Disconnect switches
- Motor control



Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMP6A16KTC	13	16	2500

Device marking

ZXMP
6A16

ZXMP6A16K

Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Drain-source voltage	V_{DSS}	-60	V
Gate-source voltage	V_{GS}	± 20	V
Continuous drain current @ $V_{GS} = 10V$; $T_{amb}=25^{\circ}C^{(b)}$ @ $V_{GS} = 10V$; $T_{amb}=70^{\circ}C^{(b)}$ @ $V_{GS} = 10V$; $T_{amb}=25^{\circ}C^{(a)}$	I_D	8.2 6.5 5.4	A
Pulsed drain current ^(c)	I_{DM}	27.2	A
Continuous source current (body diode) ^(b)	I_S	10	A
Pulsed source current (body diode) ^(c)	I_{SM}	27.2	A
Power dissipation at $T_{amb} = 25^{\circ}C^{(a)}$ Linear derating factor	P_D	4.24 33.9	W mW/°C
Power dissipation at $T_{amb} = 25^{\circ}C^{(b)}$ Linear derating factor	P_D	9.76 78	W mW/°C
Power dissipation at $T_{amb} = 25^{\circ}C^{(d)}$ Linear derating factor	P_D	2.11 16.8	W mW/°C
Operating and storage temperature range	T_j, T_{stg}	-55 to +150	°C

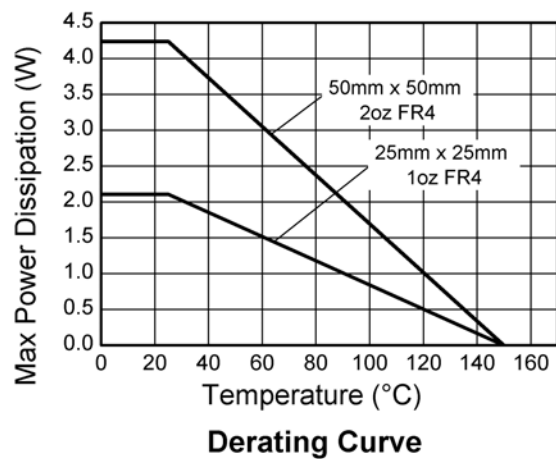
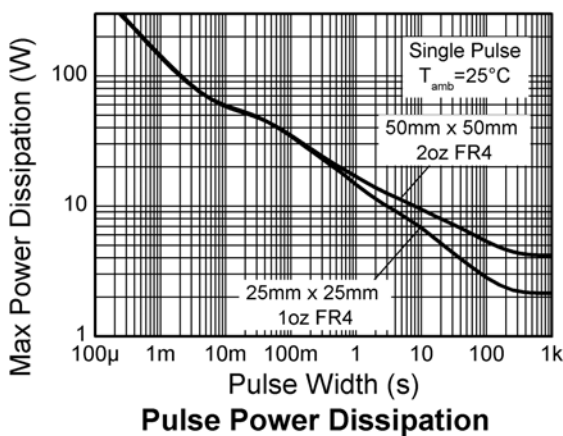
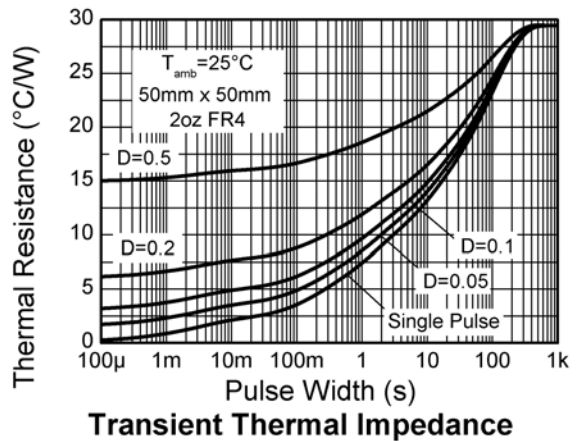
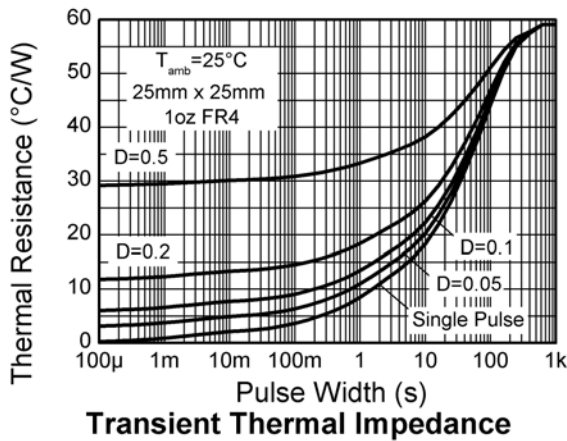
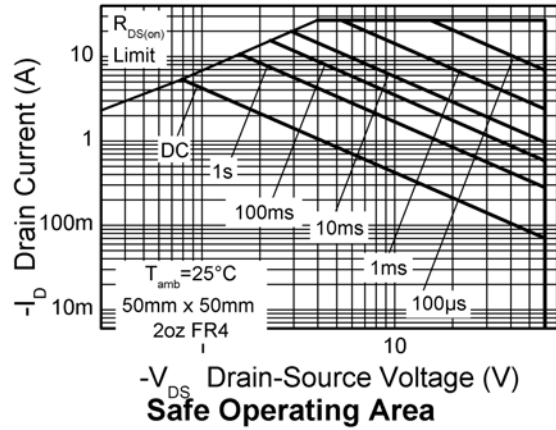
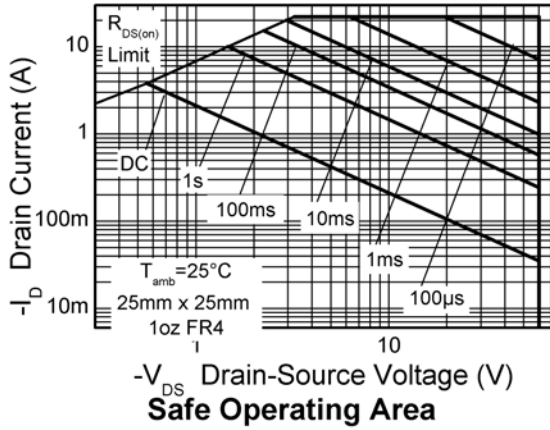
Thermal resistance

Parameter	Symbol	Limit	Unit
Junction to ambient ^(a)	$R_{\theta JA}$	29.45	°C/W
Junction to ambient ^(b)	$R_{\theta JA}$	12.8	°C/W
Junction to ambient ^(d)	$R_{\theta JA}$	59.1	°C/W

NOTES:

- (a) For a device surface mounted on 50mm x 50mm x 1.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions.
- (b) For a device surface mounted on FR4 PCB measured at $t \leq 10$ sec.
- (c) Repetitive rating 50mm x 50mm x 1.6mm FR4 PCB, $D=0.02$ pulse width=300 μ s - pulse width limited by maximum junction temperature.
- (d) For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

Thermal characteristics



ZXMP6A16K

Electrical characteristics (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Static						
Drain-source breakdown voltage	$V_{(BR)DSS}$	-60			V	$I_D = -250\mu\text{A}$, $V_{GS} = 0\text{V}$
Zero gate voltage drain current	I_{DSS}			-1.0	μA	$V_{DS} = -60\text{V}$, $V_{GS} = 0\text{V}$
Gate-body leakage	I_{GSS}			100	nA	$V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$
Gate-source threshold voltage	$V_{GS(th)}$	-1.0			V	$I_D = -250\mu\text{A}$, $V_{DS} = V_{GS}$
Static drain-source on-state resistance ^(*)	$R_{DS(on)}$			0.085	Ω	$V_{GS} = -10\text{V}$, $I_D = -2.9\text{A}$
				0.125	Ω	$V_{GS} = -4.5\text{V}$, $I_D = -2.4\text{A}$
Forward transconductance ^(*) (‡)	g_{fs}		7.2		S	$V_{DS} = -15\text{V}$, $I_D = -2.9\text{A}$
Dynamic ^(‡)						
Input capacitance	C_{iss}		1021		pF	$V_{DS} = -30\text{V}$, $V_{GS} = 0\text{V}$ $f = 1\text{MHz}$
Output capacitance	C_{oss}		83		pF	
Reverse transfer capacitance	C_{rss}		56		pF	
Switching (†) (‡)						
Turn-on-delay time	$t_{d(on)}$		3.5		ns	$V_{DD} = -30\text{V}$, $I_D = -1\text{A}$ $R_G \approx 6.0\Omega$, $V_{GS} = -10\text{V}$
Rise time	t_r		4.1		ns	
Turn-off delay time	$t_{d(off)}$		35		ns	
Fall time	t_f		10		ns	
Gate charge	Q_g		12.1		nC	$V_{DS} = -30\text{V}$, $V_{GS} = -5\text{V}$ $I_D = -2.9\text{A}$
Total gate charge	Q_g		24.2		nC	$V_{DS} = -30\text{V}$, $V_{GS} = -10\text{V}$ $I_D = -2.9\text{A}$
Gate-source charge	Q_{gs}		2.5		nC	
Gate drain charge	Q_{gd}		3.7		nC	
Source-drain diode						
Diode forward voltage ^(*)	V_{SD}		-0.85	-0.95	V	$T_j = 25^{\circ}\text{C}$, $I_S = -3.4\text{A}$, $V_{GS} = 0\text{V}$
Reverse recovery time ^(‡)	t_{rr}		29.2		ns	$T_j = 25^{\circ}\text{C}$, $I_S = -2\text{A}$, $di/dt = 100\text{A}/\mu\text{s}$
Reverse recovery charge ^(‡)	Q_{rr}		39.6		nC	

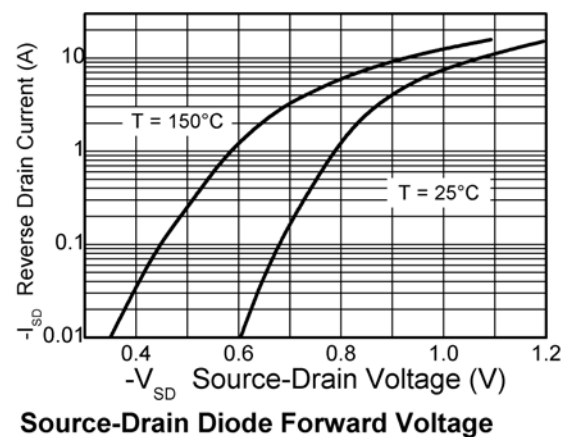
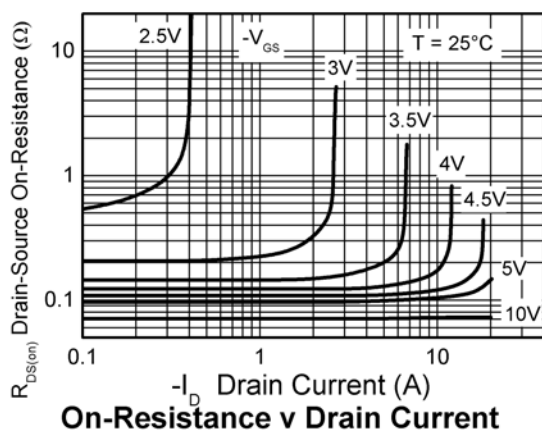
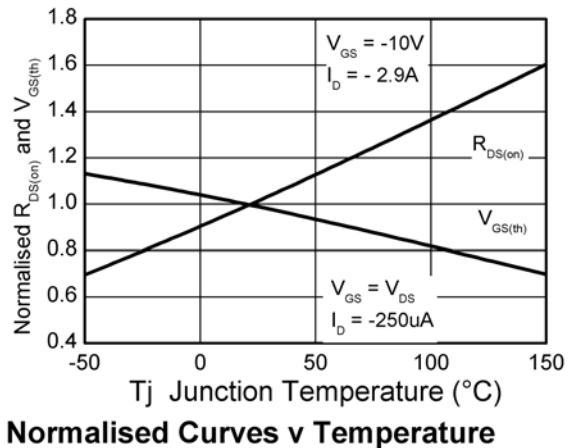
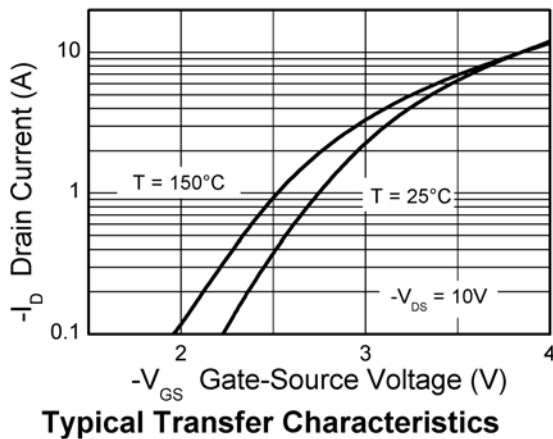
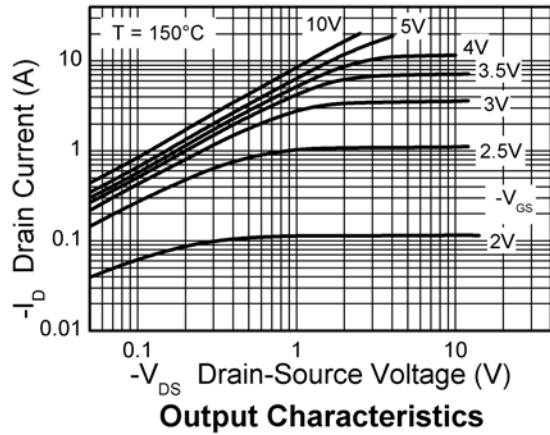
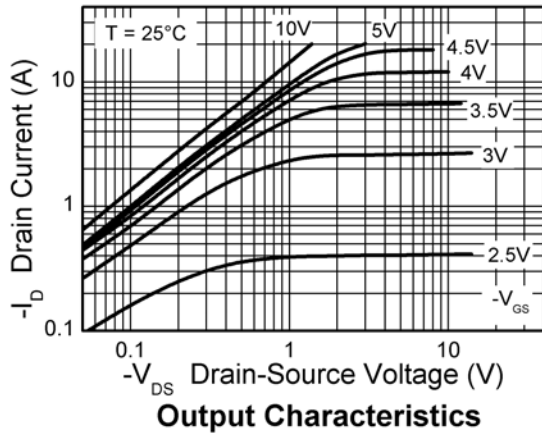
NOTES:

(*) Measured under pulsed conditions. Pulse width = $300\mu\text{s}$. Duty cycle $\leq 2\%$.

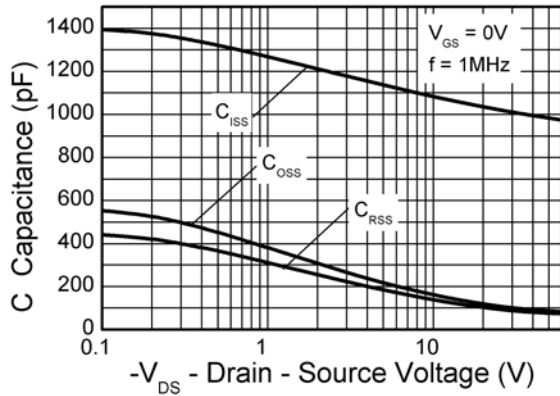
(†) Switching characteristics are independent of operating junction temperature.

(‡) For design aid only, not subject to production testing.

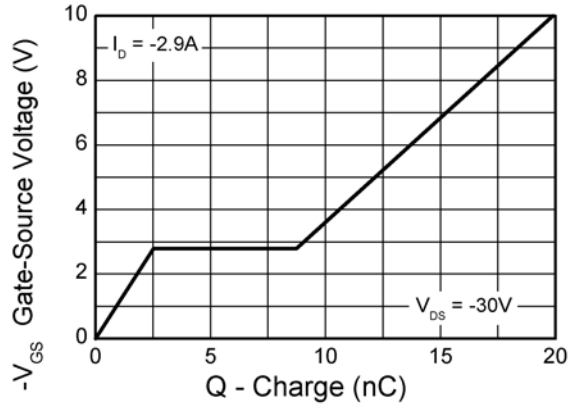
Typical characteristics



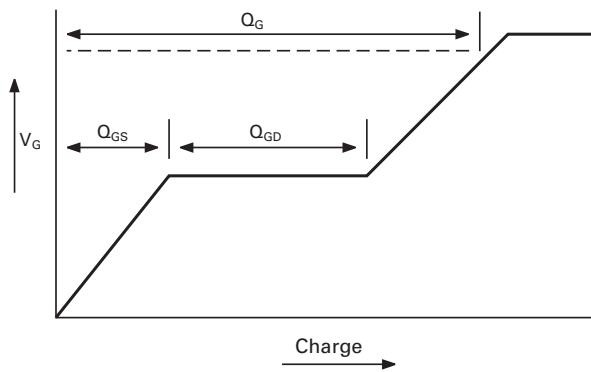
Typical characteristics



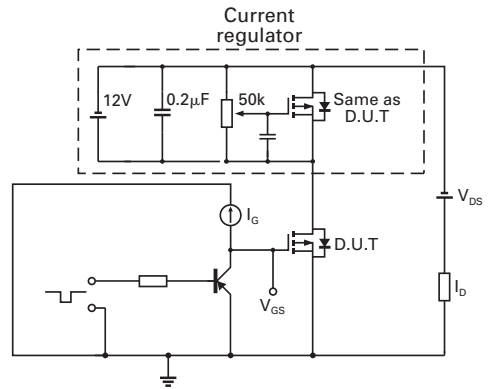
Capacitance v Drain-Source Voltage



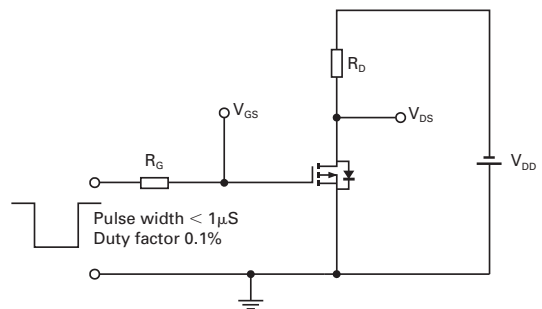
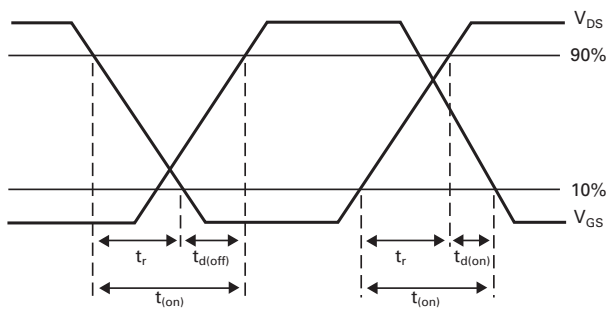
Gate-Source Voltage v Gate Charge



Basic gate charge waveform

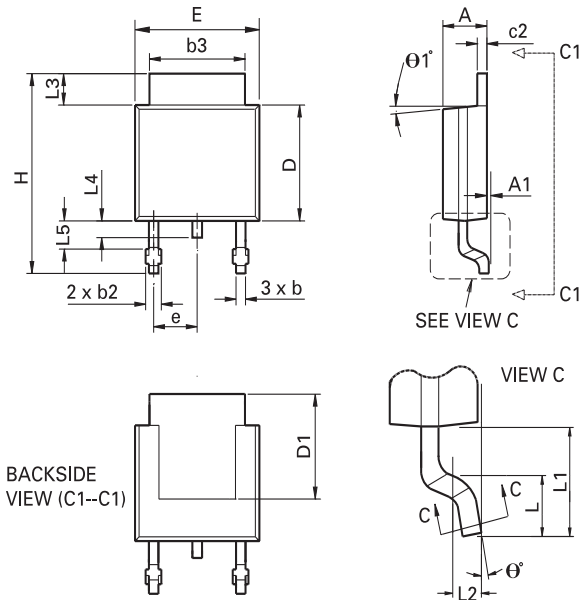


Gate charge test circuit



ZXMP6A16K

Package outline - DPAK



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min	Max	Min	Max		Min	Max	Min	Max
A	0.086	0.094	2.18	2.39	e	0.090 BSC		2.29 BSC	
A1	-	0.005	-	0.127	H	0.370	0.410	9.40	10.41
b	0.020	0.035	0.508	0.89	L	0.055	0.070	1.40	1.78
b2	0.030	0.045	0.762	1.14	L1	0.108 REF		2.74 REF	
b3	0.205	0.215	5.21	5.46	L2	0.020 BSC		0.508 BSC	
c	0.018	0.024	0.457	0.61	L3	0.035	0.065	0.89	1.65
c2	0.018	0.023	0.457	0.584	L4	0.025	0.040	0.635	1.016
D	0.213	0.245	5.41	6.22	L5	0.045	0.060	1.14	1.52
D1	0.205	-	5.21	-	theta 1°	0°	10°	0°	10°
E	0.250	0.265	6.35	6.73	theta°	0°	15°	0°	15°
E1	0.170	-	4.32	-	-	-	-	-	-

Note: Controlling dimensions are in inches. Approximate dimensions are provided in millimeters

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